TOSHIBA LED Lamp InGaAlP Red Light Emission

TLSH160

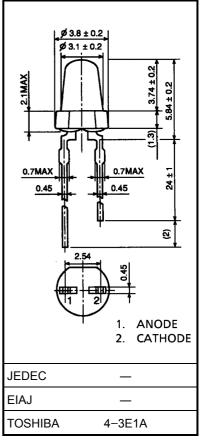
Panel Circuit Indicator

- 3.1mm diameter (T1)
- InGaAlP red LED
- Colorless transparent lens
- Low drive current, high intensity red light emission Recommended forward current: $I_F = 1 \sim 20 \text{mA}$ (DC)
- All plastic molded lens, provides an excellent on-off contrast ratio.
- Fast response time, capable of pulse operation.
- Applications: Indicator, backlight.

Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit
Forward current	I _F	50	mA
Reverse voltage	V _R	4	V
Power dissipation	P _D	125	mW
Operating temperature range	T _{opr}	-30~85	°C
Storage temperature range	T _{stg}	-40~120	°C

Unit in mm



Weight: 0.14 g

Electrical And Optical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V _F	I _F = 20mA	_	2.1	2.5	V
Reverse current	I _R	V _R = 4V	_	_	50	μΑ
Luminous intensity	I _V	I _F = 20mA (Note)	2720	4500	_	mcd
Peak emission wavelength	λ _P	I _F = 20mA	_	623	_	nm
Spectral line half width	Δλ	I _F = 20mA	_	15	_	nm
Dominant wavelength	λd	I _F = 20mA	_	613	_	nm

(Note): Lamps are classified into the following ranks according to their luminous intensity. Measurement tolerance for each limit is ±15%.

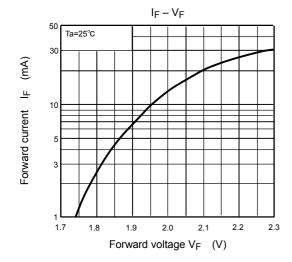
U: 3200~6400mcd, V: 5600~11200mcd, W: 8500~23000mcd

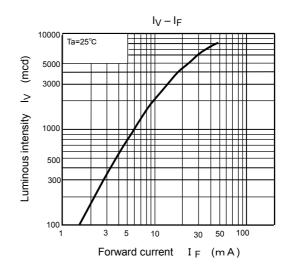
Precaution

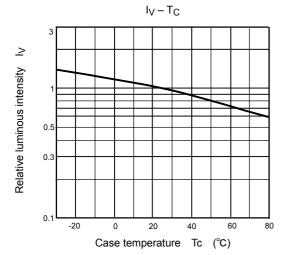
Please be careful of the followings

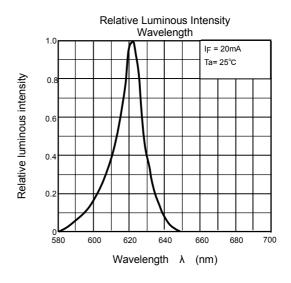
- Soldering temperature: 260°C max Soldering time: 3 s max (Soldering portion of lead: Up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light. If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.

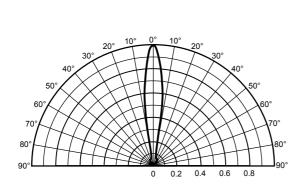
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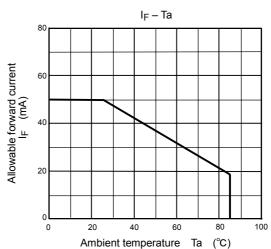




Radiation Pattern

Ta=25°C

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RESTRICTIONS ON PRODUCT USE

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